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# ABSTRACT

The present invention provides a method for evaluating a configuration of a wafer from a different viewpoint from the conventional SFQR or the like, a wafer with less troubles in an exposure system or the like, and a sorting method for a good quality wafer. The present invention comprises the steps of: obtaining plural wafer configuration profiles of from the central portion of a wafer to the edge portion thereof along the entire periphery thereof at a prescribed angular space; providing a first region for calculating a reference line for each of the profiles in the central side of the wafer; calculating the reference line in the first region; further providing a second region in the peripheral side of the wafer outside the first region; extrapolating the reference line calculated in the first region to the second region; analyzing a value (an actually measured value – a reference value) obtained by subtracting the reference line (the reference value) in the second region from a configuration (the actually measured value) in the second region; calculating the maximum value among the values as a surface characteristic A and the minimum value among the values as a surface characteristic B; and evaluating configuration uniformity in the peripheral portion of the wafer from plural surface characteristics A and surface characteristics B obtained along the entire peripheral portion of the wafer.